AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0015] beginning on page 5, as follows:

[0015] Such a thermal transient suppression material is disclosed by U.S. Patent Application Serial No. 10/075,981, now U.S. Patent 6,703,128 B2, entitled "Thermally-Capacitive Phase Change Encapsulant for Electronic Devices," assigned to the assignee of the present invention, the disclosure of which is hereby incorporated herein by reference. This exemplary material includes metallic alloy particles that provide heat absorption through a solid-to-liquid phase change while having a base material that maintains the form of a semisolid gel so that the molten metallic particles are contained by the overall material structure without requiring a physical closed barrier.

Please amend paragraph [0027] beginning on page 7, as follows:

[0027] Fig. 1 is a cross-sectional view of first exemplary electronic assembly 10 illustrating two exemplary thermal dissipation configurations. On the left, device 14 is shown thermally coupled with pedestal 32, thermal coupling member 56, ~~heat tube pedestal 30,~~ heat ~~tube~~ pipe 28, and suppression material 34. On the right, device 12 is shown thermally coupled with pedestal 30, heat ~~tube 28~~ pipe 26, and suppression material 34. Fig. 2 is an exploded perspective view of first electronic assembly 10 which includes only the first exemplary thermal dissipation configuration which is illustrated on the left side of Fig. 1.

Please amend paragraph [0030] beginning on page 8, as follows:

[0030] Referring to Figs. 1 and 2, first electronic device 12 is thermally coupled with first heat pipe 26. Specifically, first surface 36 of first electronic device 12 is thermally coupled with heat pipe 26. The thermal coupling may occur by direct physical

contact between heat pipe 26 and first surface 36, or may be provided through another material or structure, for example, thermally conductive interface potting material 27 which ensures ~~no~~ against any thermal conductivity limiting physical gaps between heat pipe 26 and first surface 36.

Please amend paragraph [0032] beginning on page 8, as follows:

[0032] Elastomeric spring 42 may be located between first case portion 22 and first heat pipe 26 in order to provide a force against heat pipe 26 to hold it in firm thermal contact with first electronic device 12. Elastomeric spring 42 may be, for example, a resilient polymer material or another compressible material which is resilient to and possibly conducts thermal energy. As shown in Figs. 1 and 2, a recess 44 may be formed in first case portion 22 to receive elastomeric spring 42, thereby holding the spring in position and alignment with heat tube 26 and electronic device 12.

Please amend paragraph [0033] beginning on page 9, as follows:

[0033] Referring briefly to Fig. 2, heat pipe 28 includes a first segment 50 and a second segment 52. Heat pipe 28 may be similar to heat pipe 26 except that heat pipe 28 includes a circular rather than a flattened oval cross-section along segment 50. Referring again to Fig. 1, first segment 50 of heat pipe 26 is in contact with first electronic device 12 and absorbs heat dissipated by first electronic device 12. Heat pipe 26 conducts the absorbed thermal energy along the length of heat pipe 26 to second segment 52 (not shown in Fig. 1) which may be in contact with first case portion 22 or another heat sink or dissipation device which absorbs heat from heat pipe 26.

Please amend paragraph [0036] beginning on page 10, as follows:

[0036] A thermally conductive coupling member such as first pedestal 30, may be in thermal contact with second surface 40 of first electronic device 12. In first exemplary electronic assembly 10, first pedestal 30 and second pedestal 32 are integrally formed with second case portion 24 and first case portion 22, respectively. Pedestal 30 may extend through an aperture 17 defined by ~~through~~ substrate 16 and be thermally coupled with ~~second~~ third surface 40, or another portion of first electronic device 12. Alternatively, pedestal 30 may be thermally coupled through substrate 16, or another material capable of sufficient thermal conduction. Thermally conductive interface material 31 may also be provided between device 12 and pedestal 30 to ensure good thermal conductivity.

Please amend paragraph [0040] beginning on page 11, as follows:

[0040] Elastomeric spring 42 resting in second spring ~~rest~~ recess 46 of second case portion 24 holds second heat pipe 28 and thermal coupling member 56 in thermal contact with a first side of second electronic device 14. Pedestal 32, which in first exemplary electronic assembly 10 is integrally formed with first case portion 22, is coupled with second electronic device 14 on a side opposite second heat pipe 28. Pedestal 32 may provide a thermal conduction path as well as mechanical support of substrate 16 and/or second electronic device 14. In order to achieve thermal contact between device 14 and pedestal ~~22~~ 32, pedestal 32 may also extend through one of apertures 17 defined through substrate 16.

Please amend paragraph [0043] beginning on page 12, as follows:

[0043] Elastomeric spring 142 may be received in a recess 146 or 144 of first case portion 122 and second case portion 124, respectively. Elastomeric spring 142 may be

used to firmly thermally couple heat pipe 48 with thermal coupling member 156 and/or electronic device 112. On the side opposite heat pipe 48, electronic device 112 may also be thermally coupled to first case portion 122 or second case portion 124, or a pedestal (not shown) such as pedestal 30 or 32 of Figs. 1 and 2, or other heat dissipation device coupled thereto or independent thereof.

Please amend paragraph [0044] beginning on page 12, as follows:

[0044] ~~To~~ Referring alternatively to Figs. 2 and 3, to further provide effective heat dissipation, case portions 22, 122 and 24, 124 may also include cooling fins 58, 158 and 60, 160, respectively, for radiating heat from case portions 122 and 124 into the surrounding atmosphere. As can be understood from ~~Fig. 2~~ Fig. 3, case portions 122 and 124 not only provide heat dissipation, but may also provide for enshrouding, packaging or other protection of the components of second exemplary electronic assembly 100 as case portions 122 and 124 provide a clamshell style case 120 that enshrouds the various components.